Product End-of-Life Disassembly Instructions

Product Category: *Servers*
Marketing Name / Model [List multiple models if applicable.]
HPE ProLiant DL365 Gen11 Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.
1.3 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	8
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected	3 to 8
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices	1 to 15
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

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Item Description	Notes	Quantity of items included in product
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-10
Torx Driver	T-15
Torx Driver	T-20
Hex Socket	3/16
Screwdriver Cross Type	PH-0
Screwdriver Cross Type	PH-1
Screwdriver Flat Type	4.0
Sharp Nose Pliers	
Soldering Iron	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect all cables
2. Remove System Fans
3. Remove CPU Heatsink and CPU
4. Remove DIMM Guard
5. Remove RTC battery and Megacell
6. Remove Main Board
7. Remove Latch Ear and Front Panel
8. Separate front end and base
9. 8SFF front end tear down
10. 2SFF cage tear down
11. Ear module tear down
12. USB cage tear down
13. Media cage tear down
14. Remove ODD module
15. Remove LP Riser Cage and PCIE adaptor
16. Remove FH Riser Cage and PCIE adaptor

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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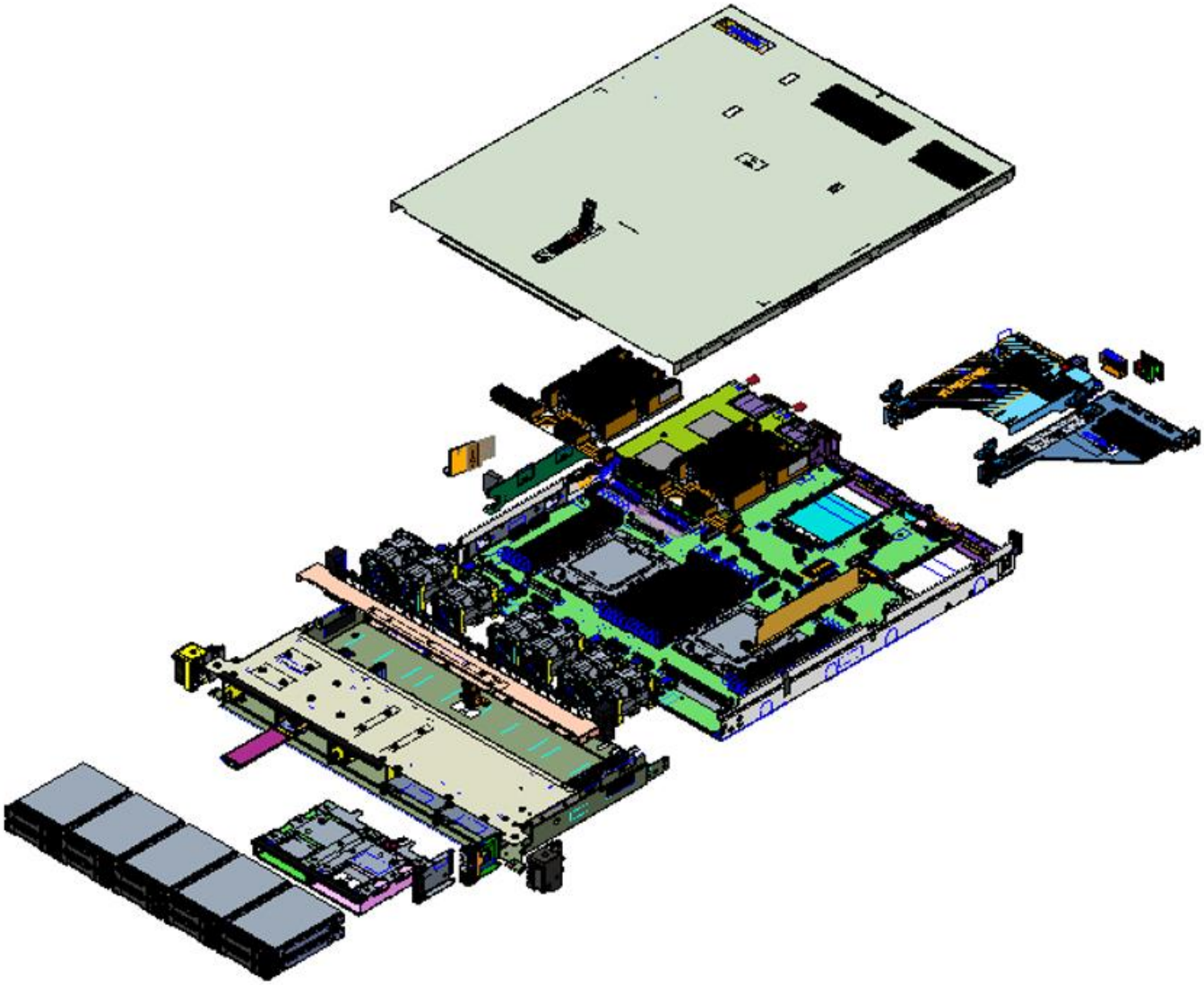
Attachment 1–Disconnect all cable



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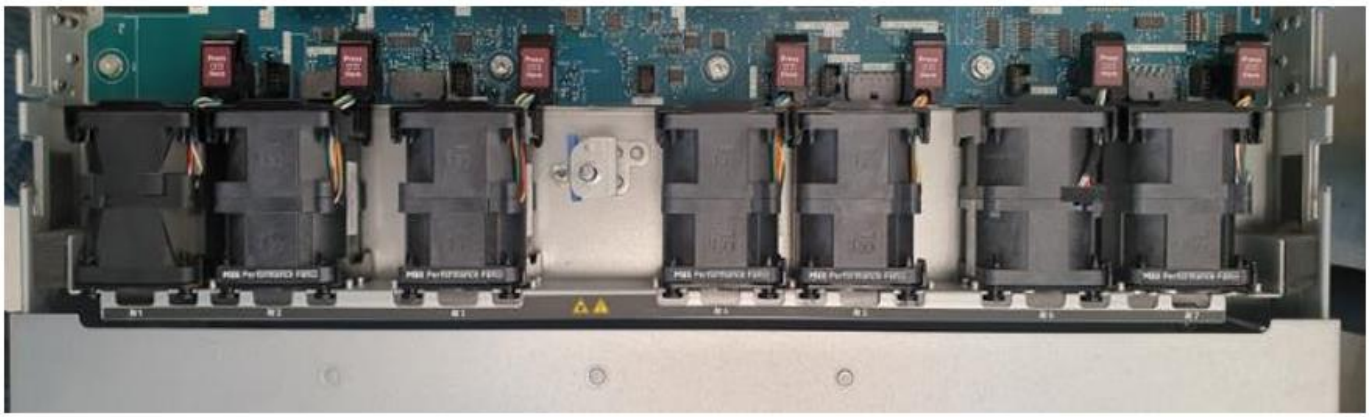
Attachment 2 Remove System Fans



Attachment 3- Remove CPU Heatsink and CPU

1. Remove CPU Heatsink by using T20 screwdriver.



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2. Remove CPU cover by using T20 screwdriver then Remove the CPU



Attachment 4 - Remove RTC battery & Megacell

1. To remove RTC battery by pushing the latch as drawing below.





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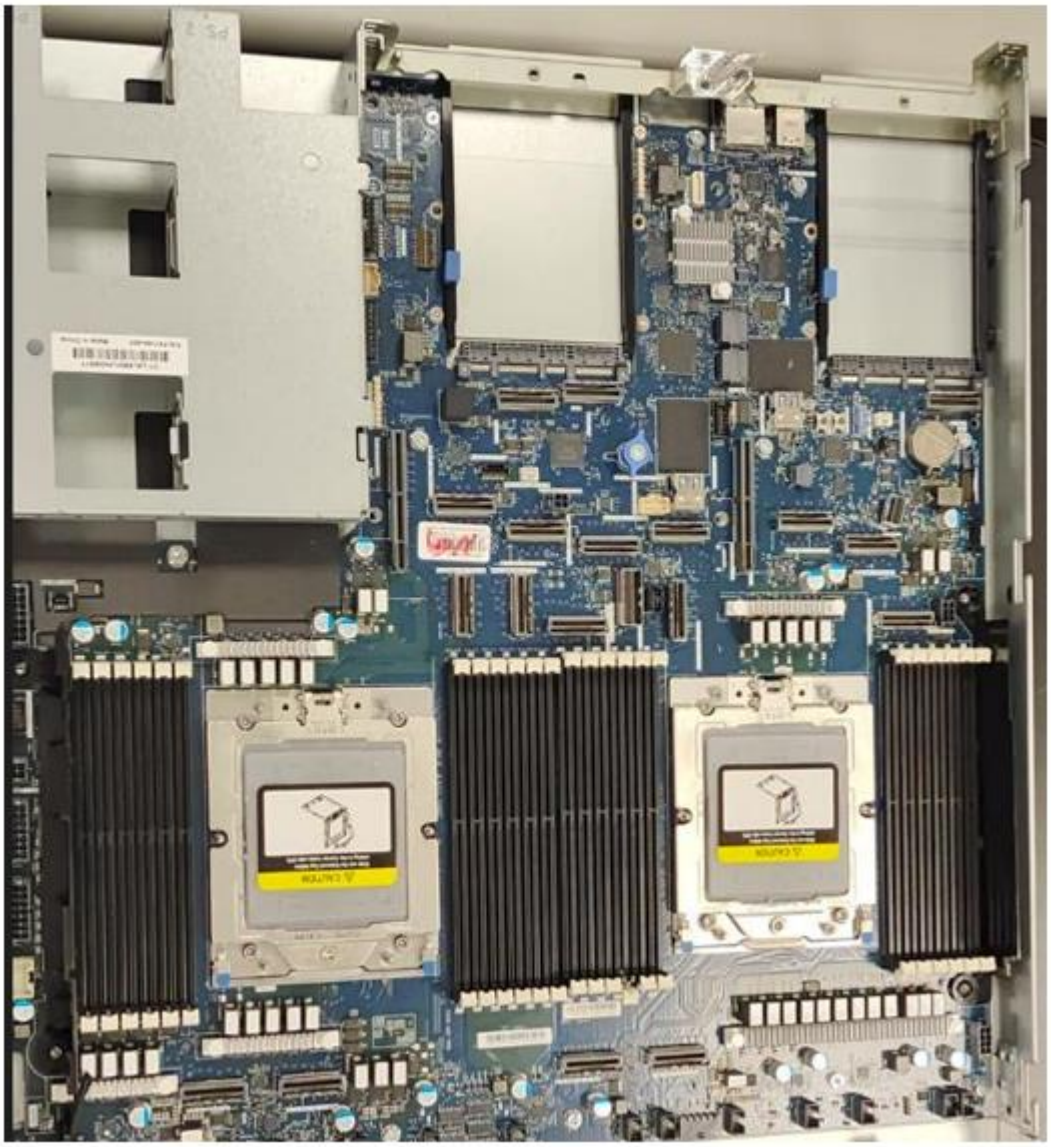
Attachment 5 - Remove MB

1. Loose the thumb screw to release MB from chassis



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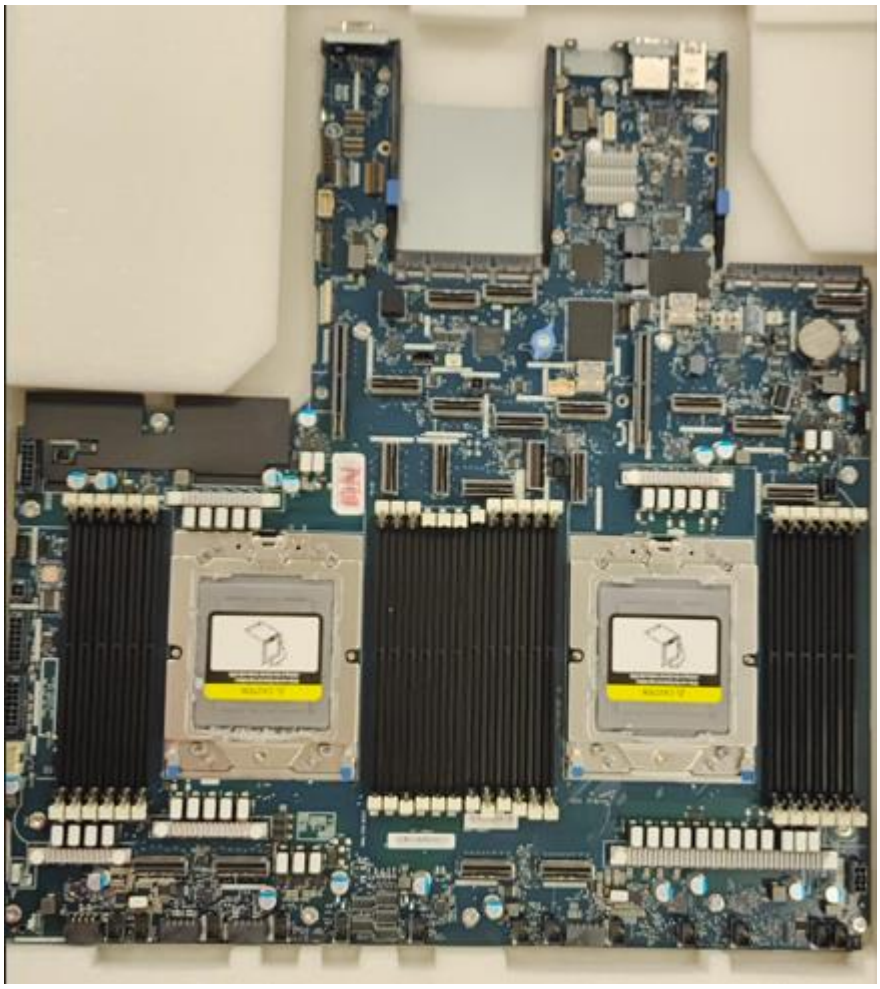
2. Use T-15 screwdriver and 3/16 Hex socket to remove screws to release MB from MB tray





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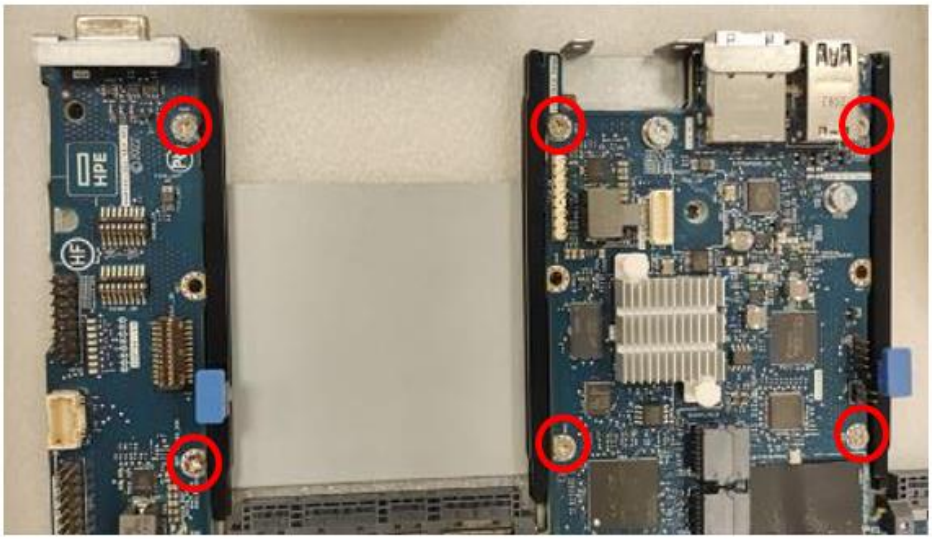
3. Use PH-1 screwdriver to remove the OCP MB rail

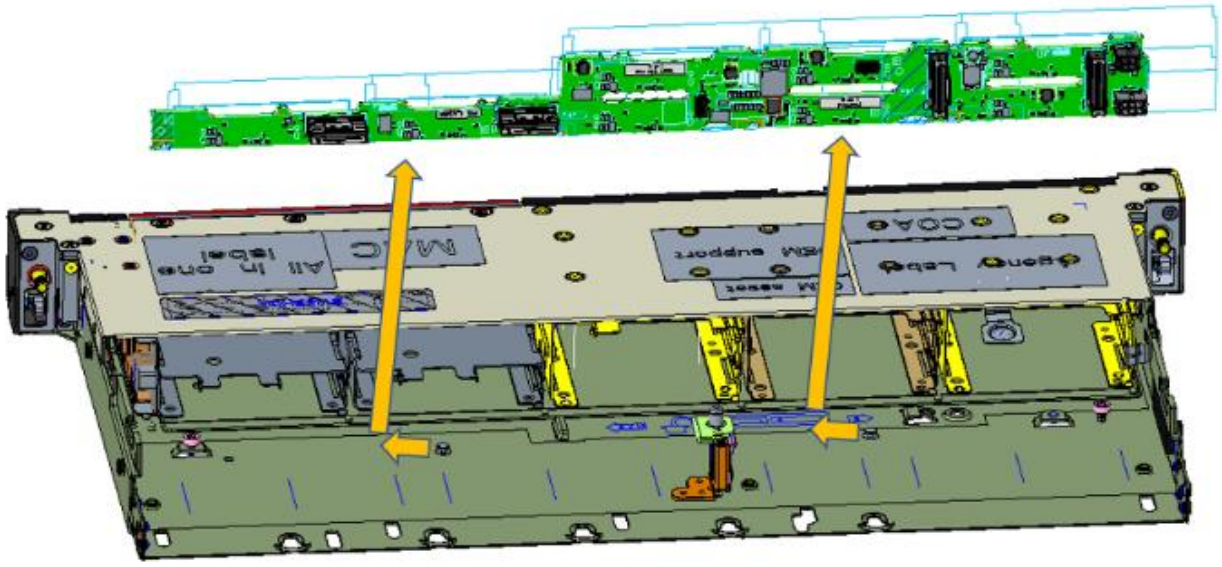


Attachment 6 – 8SFF front end tear down

1. Remove BP single and power cable. (8SFF)



2. Slide the BP board to remove. (8SFF)



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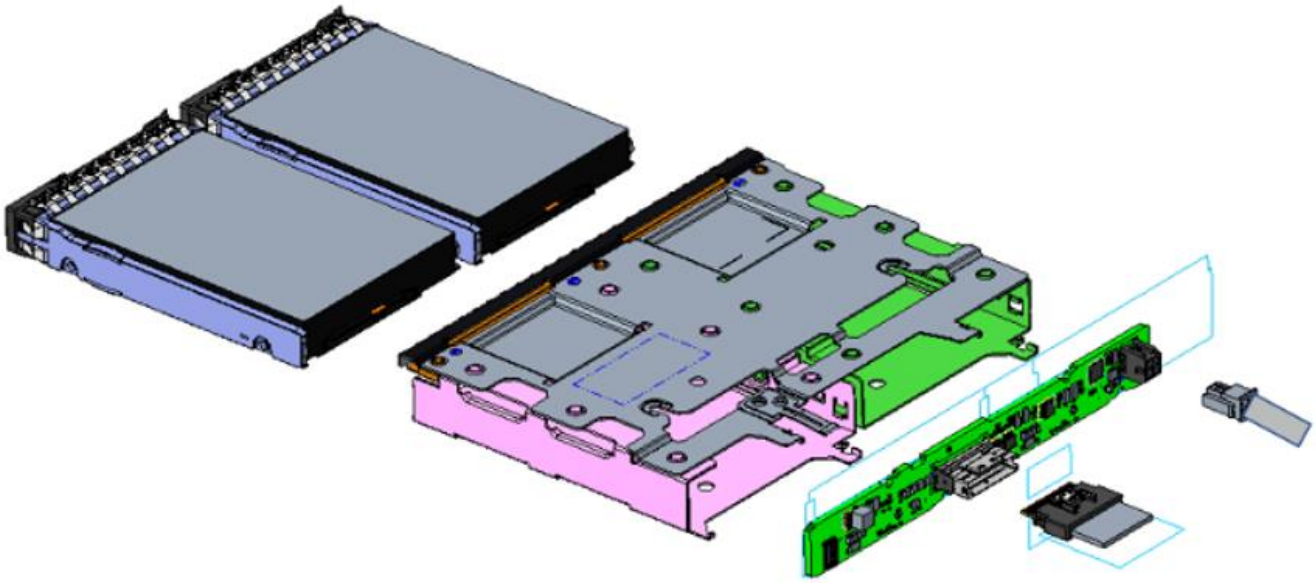
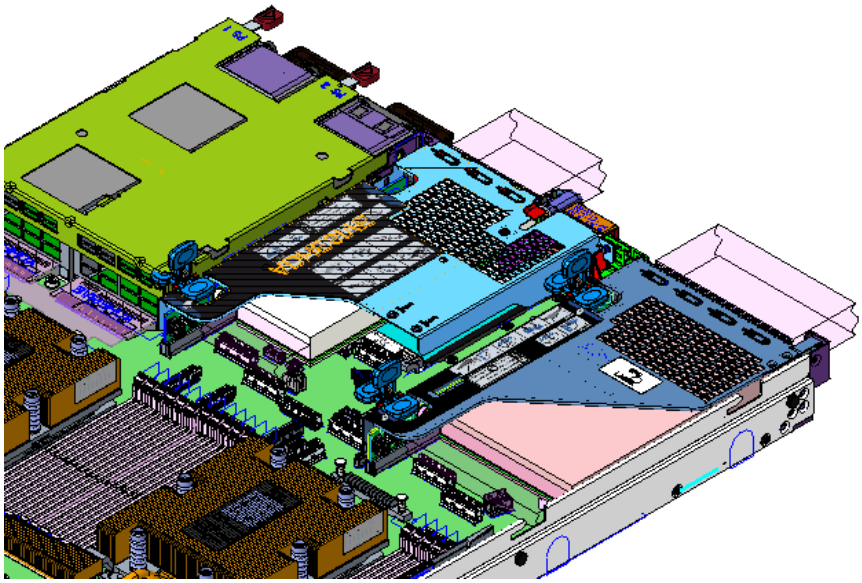
Attachment 7 - 2SFF cage tear down



Attachment 8–Remove LP Riser Cage and PCIE adaptor

1. Remove riser cage from MB



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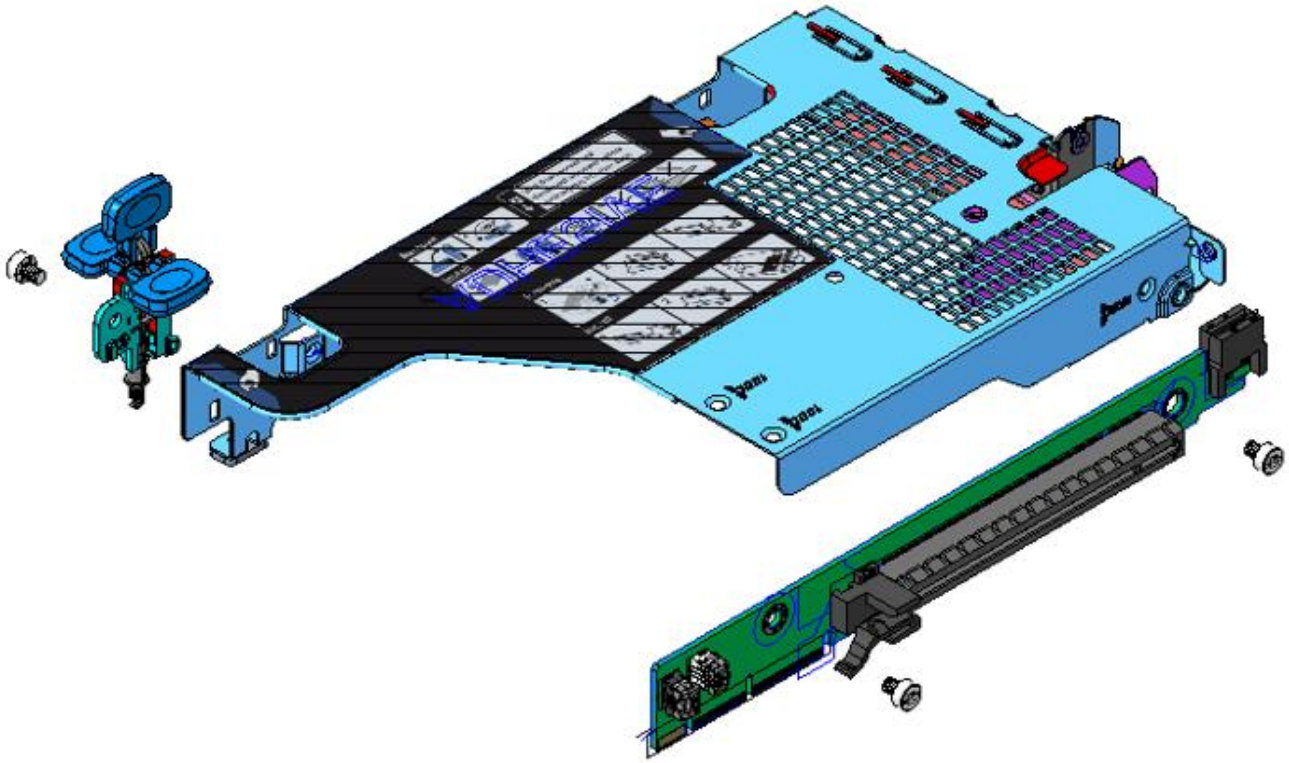
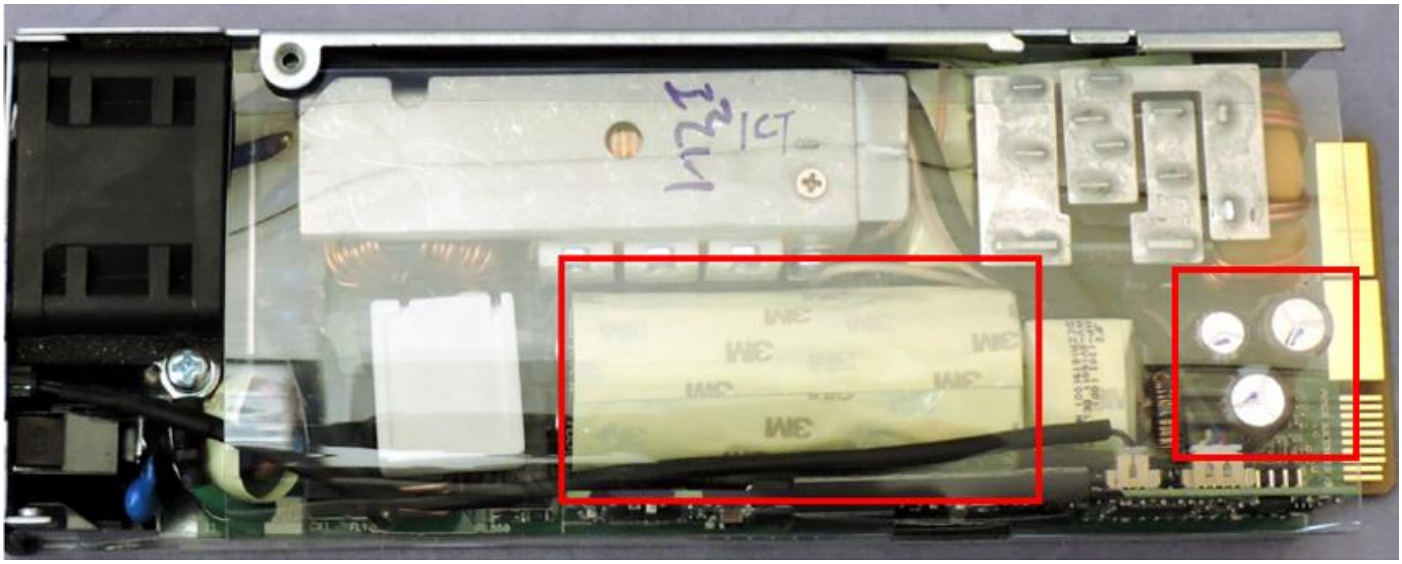
2. Remove PCIE Riser from PCIE cage.



Attachment 9 – Remove Electrolytic capacitors in PSU

1. HSTNS-PD41-1



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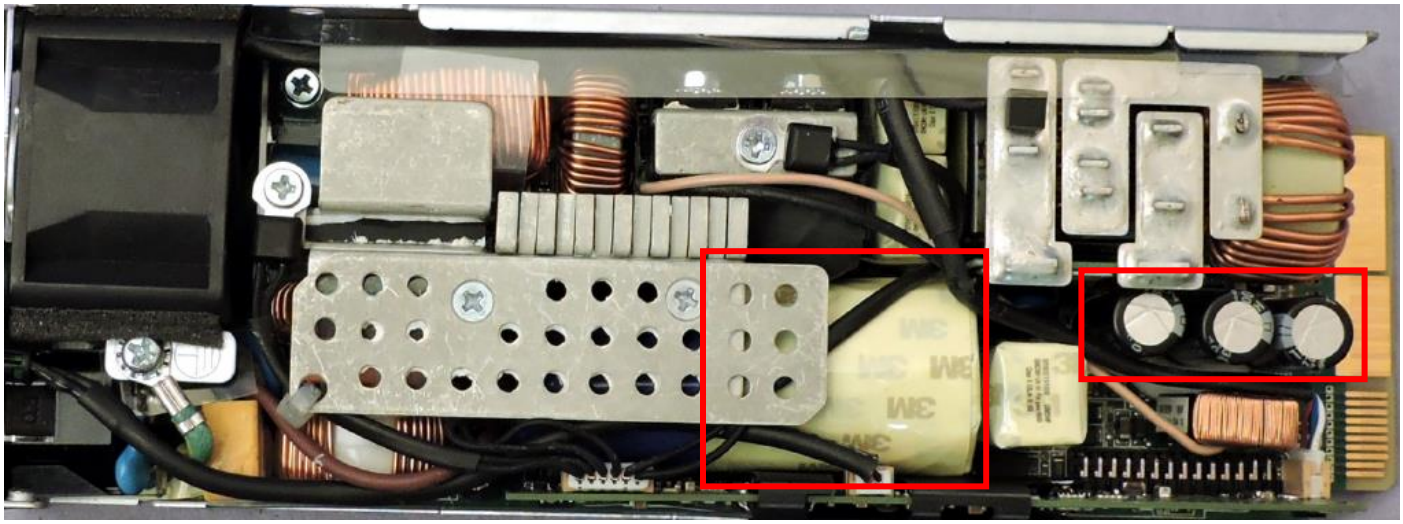
2. HSTNS-PL41-1



3. HSTNS-PC41-1



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